



SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	<i>↗</i>	2.25	2.60	2
A ₁	0.40	0.50	0.60	
D/E	31.00 BSC			
D ₁ /E ₁	29.00 REF			
e	1.00 BSC			
Øb	0.50	0.60	0.70	
aaa	<i>↗</i>	<i>↗</i>	0.20	
ccc	<i>↗</i>	<i>↗</i>	0.35	
ddd	<i>↗</i>	<i>↗</i>	0.30	
eee	<i>↗</i>	<i>↗</i>	0.10	
L	<i>↗</i>	<i>↗</i>	29.05	
M	30			
REF.	JEDEC MS-034-AAN-1			

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.

900-BALL FINE PITCH BGA (FG900/FGG900)

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
03/12/09	1.3	Removed note 3 regarding component land diameter. This dimension is specified in UG112 , <i>Device Package User Guide</i> under Recommended PCB Design Rules.

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